

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Ikuya MIYAZAWA

Application No.: New U.S. Patent Application

Filed: March 5, 2002

Docket No.: 112155

For: SOLDERING METHOD, SOLDERING DEVICE, AND METHOD AND DEVICE OF
FABRICATING ELECTRONIC CIRCUIT MODULE



INFORMATION DISCLOSURE STATEMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Pursuant to 37 CFR §1.56, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached PTO-1449. Unless otherwise indicated herein, one copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

- ☒ 1. This Information Disclosure Statement is being filed (a) within three months of the U.S. filing date of this non-CPA application, OR (b) before the mailing date of a first Office Action on the merits in the present application. No certification or fee is required.
- ☒ 2. An English-language Abstract of the non-English language reference is attached hereto.

Respectfully submitted,

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